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PATENT



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C. Meade  
Attorney Reference Number 6047-61466  
Application Number 10/002,779

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Response Under 37 C.F.R. § 1.116 Expedited Procedure**

In re application of: Agarwal et al.

Art Unit: 2818

Application No. 10/002,779

Filed: October 29, 2001

For: METHODS FOR FORMING AND  
INTEGRATED CIRCUIT STRUCTURES  
CONTAINING RUTHENIUM AND  
TUNGSTEN CONTAINING LAYERS

Examiner: David Vu

Date: April 9, 2003

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on April 9, 2003 as First Class Mail in an envelope addressed to: BOX AF COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

Attorney for Applicant

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**REMARKS**

In response to the Office action of March 14, 2003, reconsideration of the subject application is requested in view of the following remarks. Claims 51-55 and 72-73 are pending.

The subject application is a continuation of Application 09/590,795 and the specification has been amended as required to claim priority under 35 U.S.C. § 120. Acknowledgement of this claim for domestic priority is requested.

Accompanying these Remarks is a copy of an Information Disclosure Statement submitted August 21, 2002 and Applicants request that an initialed copy of the accompanying form 1449 be returned to the undersigned. Copies of the references were not provided when the Information Disclosure Statement was submitted because copies were provided in Application No. 09/590,795 from which the subject application claims priority. Additional copies of the references will be furnished upon request.

Claims 51-55 and 71-72 stand rejected under 35 U.S.C. § 112, first paragraph, as allegedly containing subject matter that was not described in the specification. This rejection is traversed. According to the Office action, the specification does not support the recitation "the ruthenium-containing layer having a non-textured surface adjacent the supporting structure." Support can be found in the specification at, for example, page 6, lines 20-25, and Figure 2. Referring to Figure 2, a roughened ruthenium layer 16 is situated on a smooth surface of a supporting structure 10. This ruthenium-containing layer can be continuous or discontinuous, but is shown as discontinuous in Figure 2. Hence, Figure 2 illustrates a ruthenium-containing layer having a non-textured surface adjacent the supporting structure as recited in claims 51-55 and 71-72. Withdrawal of this rejection is requested.

In view of the preceding remarks, claims 51-53 and 72-73 are properly allowable and action to such end is requested.

The undersigned thanks Examiner Vu for his consideration in the telephone interview.

Respectfully submitted,

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